8341

No-Clean Flux Paste

8341 is designed for lead-free alloys, but also works well with conventional leaded solders. This tacky no-clean flux paste uses a mix of rosin, thickener, and high-grade synthetically refined resin. The flux provides fast and widespread wetting during soldering and leaves non-conductive and non-tacky residues.

This solder flux paste is ideal for solder touch-ups, repairs, or reworks of surface mount assemblies

Features & Benefits

Soldering flux paste for electronics

Excellent wettability

Clear, non-conductive, and non-tacky residues

Usable for both lead-free and leaded alloys

Meets J-STD-004B ROL1 classification

RoHS-compliant

Available Packaging

Part #	Packaging	Net Vol.	Net Wt.
8341-10ML	Syringe	10 mL	9.80 g
8341-50ML	Jar	50 mL	49.0 g

Storage and Handling

Store between 18 and 27 ˚C in a dry area, away from sunlight (see SDS).

Properties

Solids %	99.2%	IPC-TM-650 2.3.34
Flux Classification	ROL1	J-STD-004B, MIL-F-14256F
Flux Type	Rosin	J-STD-004B
Flux Activity	Low	J-STD-004B
Copper Mirror	Pass	IPC-TM-650 2.3.32
Corrosion Test	Pass	IPC-TM-650 2.6.15
Flux Residue Dryness	Pass	IPC-TM-650 2.4.47
Surface Insulation Resistance (SIR)	Pass	IPC-TM-650 2.6.3.7
Electromigration (ECM), IR Initial @ 96 h IR Initial @ 596 h	Pass Pass	Bellcore GR-78-CORE 13.1.4
Acid Number (mgKOH/g sample)	126	IPC-TM-650 2.3.13
Halides (by weight)	<0.5%	IPC-TM-650 2.3.35
Halogen Content	0.81%	EN 14582
Cleaning Requirements	Recommended	—
Shelf Life	2 y	—